



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



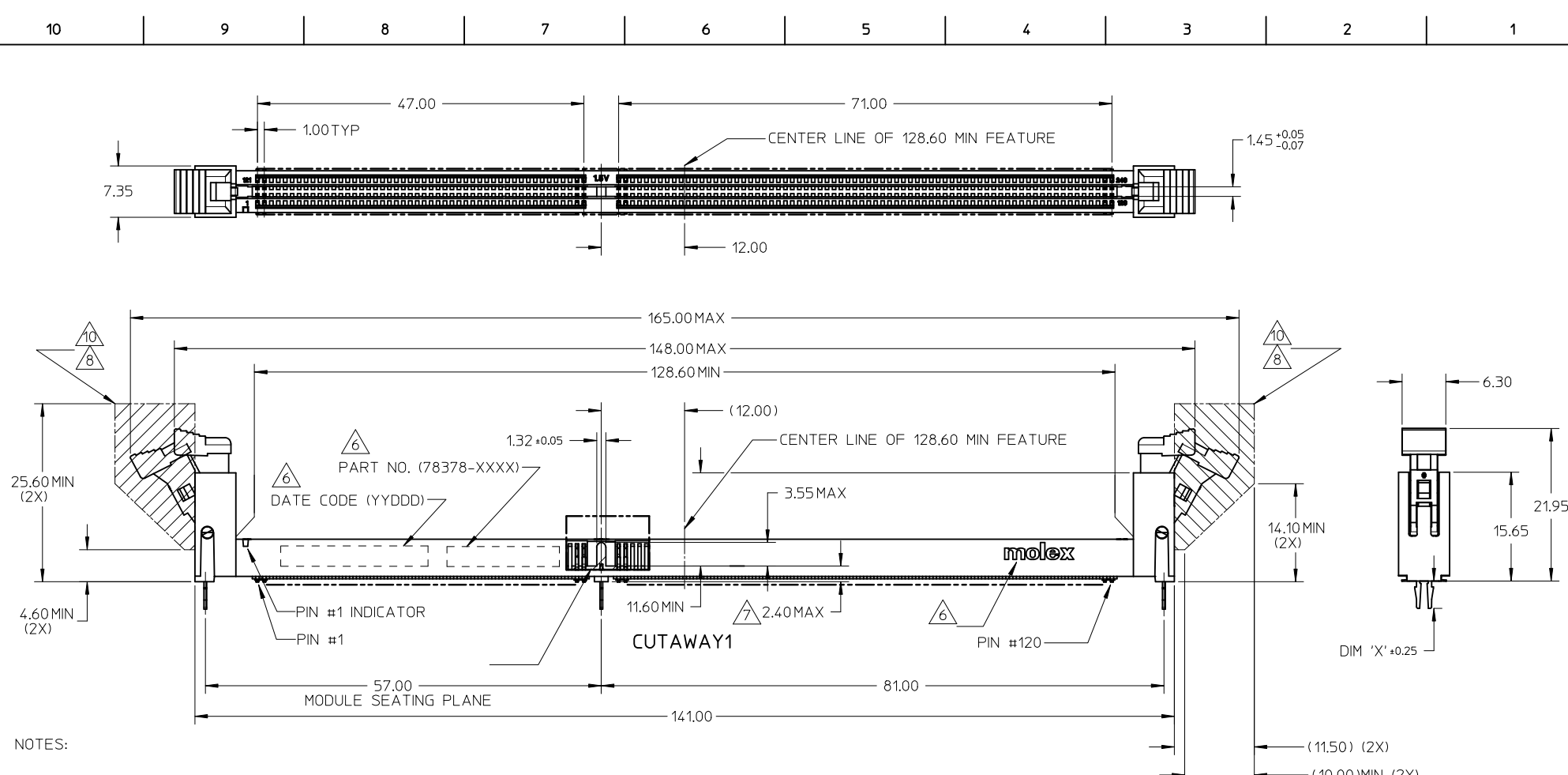
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NOTES:

- MATERIAL : HOUSING - LCP, GLASS FILLED, UL 94V-0
COLOUR : BLACK.
LATCH - NYLON, GLASS FILLED, UL 94V-0
COLOUR : SEE TABLE ON SHEET 6.
TERMINAL : COPPER ALLOY.
- FINISHES - SEE TABLE ON SHEET 6.
- PRODUCT SPECIFICATION : RPS-78507-001
- PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAY, SEE SHEET 5
- CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS (MEASURED FROM P.C. PADS).
- MOLEX LOGO, DATE & PART NO. INDICATED ON HOUSING.
- MODULE SEATING PLANE FROM TOP OF PCB.
- KEEP OUT ZONE RESERVED FOR LATCH.
- KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDED LATCHES IN OPENING POSITION) IS MOUNTED ON THE PCB.
- KEEP OUT ZONE AS PER JEDEC SO-014.

AMD. JEDEC STD. NO.	EC NO. S2011-0743	DRWN:CCIEH 2011/02/25	CHKD:CGTAN 2011/04/19	APPR:SHLENI 2011/04/19
REV	DESCRIPTION			
2				

QUALITY SYMBOLS	$\nabla_F=0$ $\nabla_E=0$ $\nabla_P=0$
-----------------	--

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± ---	± ---
ANGULAR ± 3 °		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

DIMENSION STYLE		SCALE	DESIGN UNITS
MM ONLY		NTS	METRIC
DRAWN BY	DATE	TITLE	
JAKEEMEW	2009/04/22	DDR3 DIMM, 1.00 PITCH	
CHECKED BY	DATE	240CKTS, LSP, STD LATCH	
CCTEH	2009/05/27	SMT, VERTICAL, LOWLLCR	
APPROVED BY	DATE	MATERIAL NO.	
SHLENI	2009/05/27	SEE TABLE	
MATERIAL NO.		DOCUMENT NO.	SHEET NO.
		SD-78507-001	1 OF 6

THIRD ANGLE PROJECTION	
MOLLEX MOLEX INCORPORATED	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

10 9 8 7 6 5 4 3 2 1

F

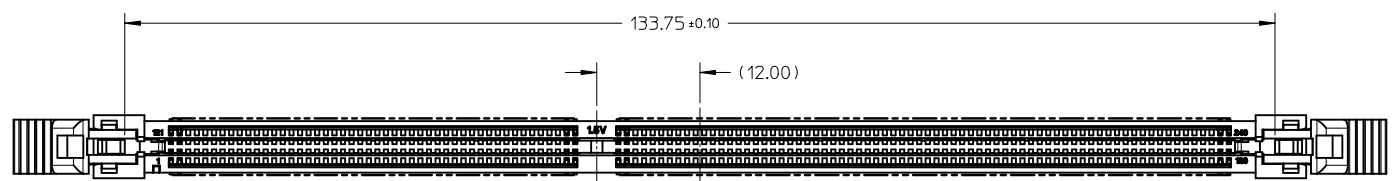
E

D

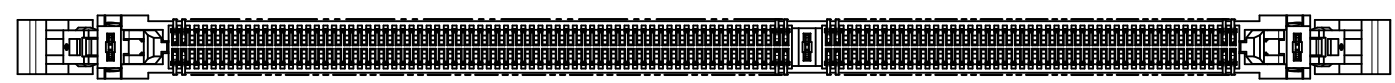
C

B

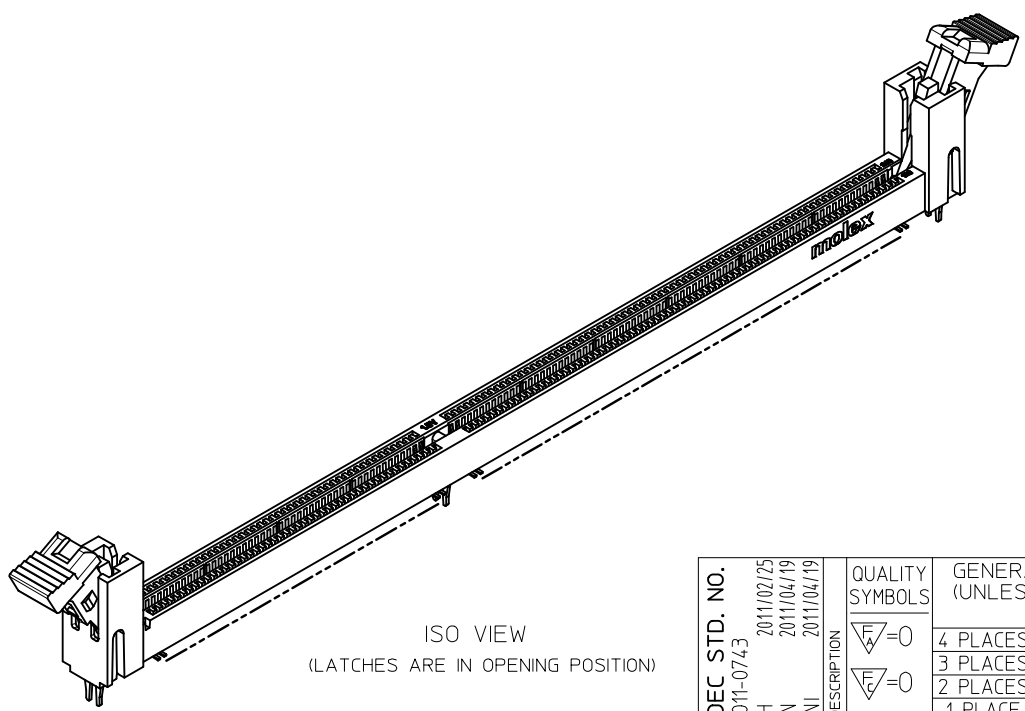
A



TOP VIEW
(LATCHES ARE IN OPENING POSITION)
CENTER LINE OF 128.60 MIN FEATURE



BOTTOM VIEW
(LATCHES ARE IN OPENING POSITION)



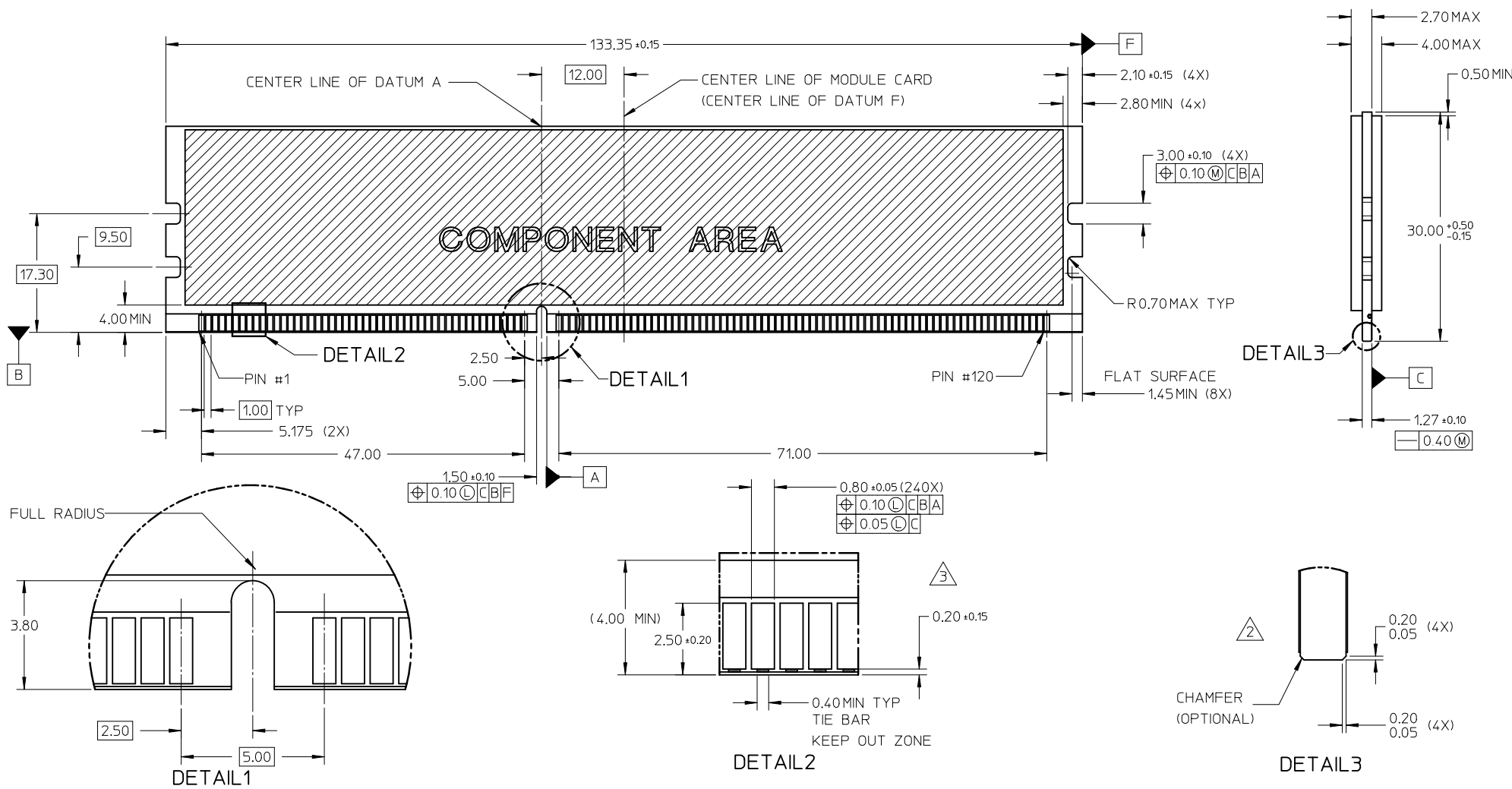
ISO VIEW
(LATCHES ARE IN OPENING POSITION)

AMD, JEDEC STD. NO. EC NO: S2011-0743 DRAWN: CCTEH 2011/02/25 CHKD: CGTAN 2011/04/19 APPR: SHLENI 2011/04/19	REV 2	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
					mm	INCH	DRAWN BY JAKEEMEW	DATE 2009/04/22	TITLE DDR3 DIMM, 1.00 PITCH 240CKTS, LSP, STD LATCH SMT, VERTICAL, LOWLLCR	
				4 PLACES	± ---	± ---	CHECKED BY CCTEH	DATE 2009/05/27	APPROVED BY SHLENI	
				3 PLACES	± ---	± ---	DATE 2009/05/27		MATERIAL NO.	
				2 PLACES	± 0.20	± ---	DATE 2009/05/27		DOCUMENT NO.	
				1 PLACE	± ---	± ---	DATE 2009/05/27		SHEET NO.	
				ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-78507-001
						SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		2 OF 6

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

MODULE CARD
 DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS
 (JEDEC MO-269, ISSUE B, APRIL/06)

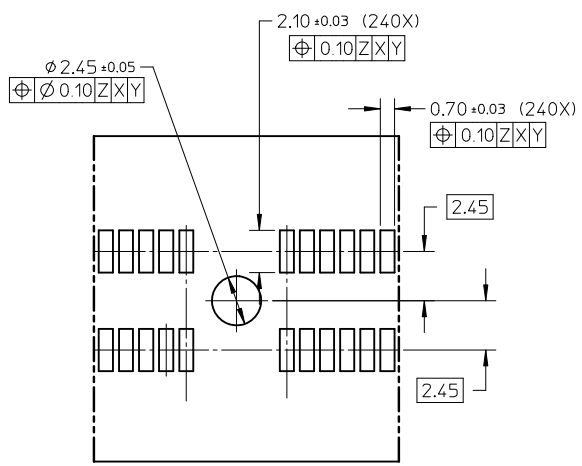
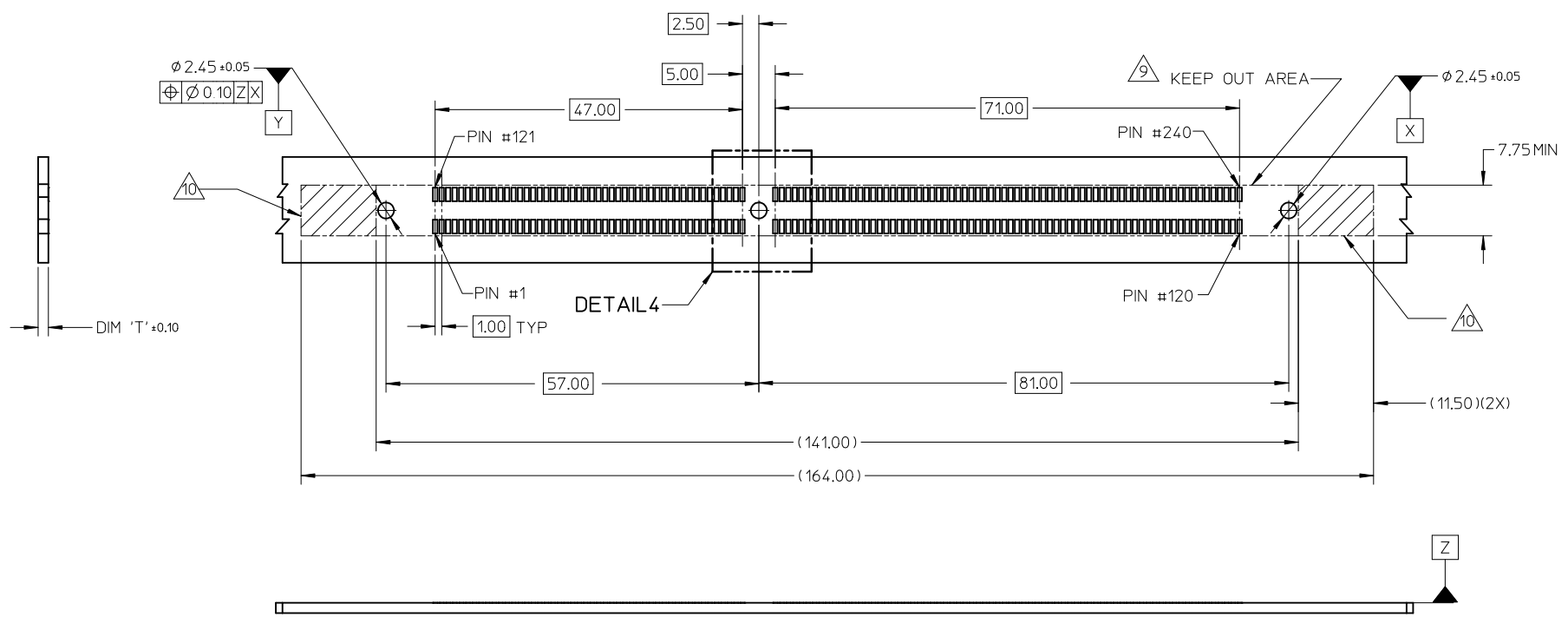


- NOTES:
- RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN OVER 2.00 MICROMETERS NICKEL.
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT.
 - CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS.
 - LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

AMD, JEDEC STD. NO. EC NO: S2011-0743 DRW:CCTEH 2011/02/25 CHKD:CGTAN 2011/04/19 APPR:SHLENI 2011/04/19	QUALITY SYMBOLS F _A =0 F _G =0 F _P =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY JAKEEMEW	DATE 2009/04/22	TITLE DDR3 DIMM, 1.00 PITCH 240CKTS, LSP, STD LATCH SMT, VERTICAL, LOWLLCR			
		4 PLACES	± ---	± ---	CHECKED BY CCTEH	DATE 2009/05/27	MOLEX INCORPORATED			
		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2009/05/27	DOCUMENT NO. SD-78507-001	SHEET NO. 3 OF 6		
			2 PLACES	± 0.20	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
			1 PLACE	± ---	± ---	SEE TABLE				
			ANGULAR ± 3 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



DETAIL4

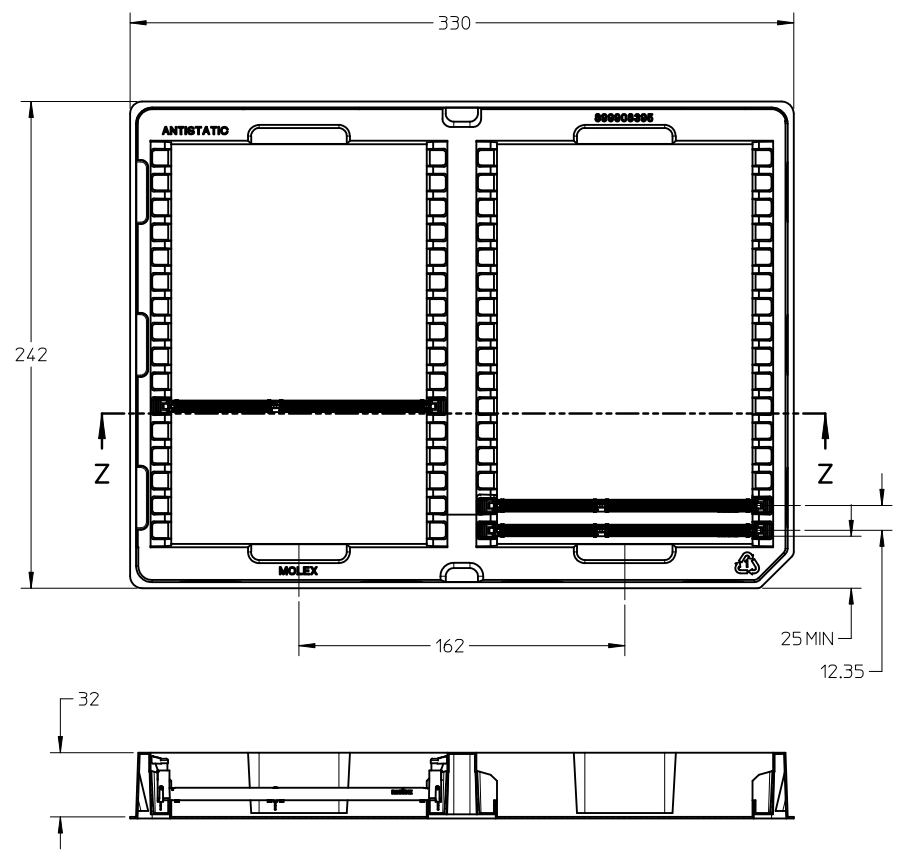
RECOMMENDED PCB THICKNESS = 1.57mm ~ 3.18mm
 RECOMMENDED STENCIL THICKNESS = 150 MICROMETERS

AMD, JEDEC STD. NO. EC NO: S2011-0743 DRWN: CCTEH 2011/02/25 CH'KD: CGTAN 2011/04/19 APPR: SHLENI 2011/04/19 REV 2	QUALITY SYMBOLS $\nabla = 0$ $\nabla = 0$ $\nabla = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>\pm ---</td> <td>\pm ---</td> </tr> <tr> <td>3 PLACES</td> <td>\pm ---</td> <td>\pm ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>\pm ---</td> </tr> <tr> <td>1 PLACE</td> <td>\pm ---</td> <td>\pm ---</td> </tr> </tbody> </table> ANGULAR $\pm 3^\circ$		mm	INCH	4 PLACES	\pm ---	\pm ---	3 PLACES	\pm ---	\pm ---	2 PLACES	± 0.20	\pm ---	1 PLACE	\pm ---	\pm ---	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																		
	4 PLACES	\pm ---	\pm ---																		
	3 PLACES	\pm ---	\pm ---																		
2 PLACES	± 0.20	\pm ---																			
1 PLACE	\pm ---	\pm ---																			
DRAWN BY JAKEEMEW	DATE 2009/04/22	TITLE DDR3 DIMM, 1.00 PITCH 240CKTS, LSP, STD LATCH SMT, VERTICAL, LOWLLCR																			
CHECKED BY CCTEH	DATE 2009/05/27	MOLEX INCORPORATED																			
APPROVED BY SHLENI	DATE 2009/05/27	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78507-001	SHEET NO. 4 OF 6																	

9 8 7 6 5 4 3 2 1

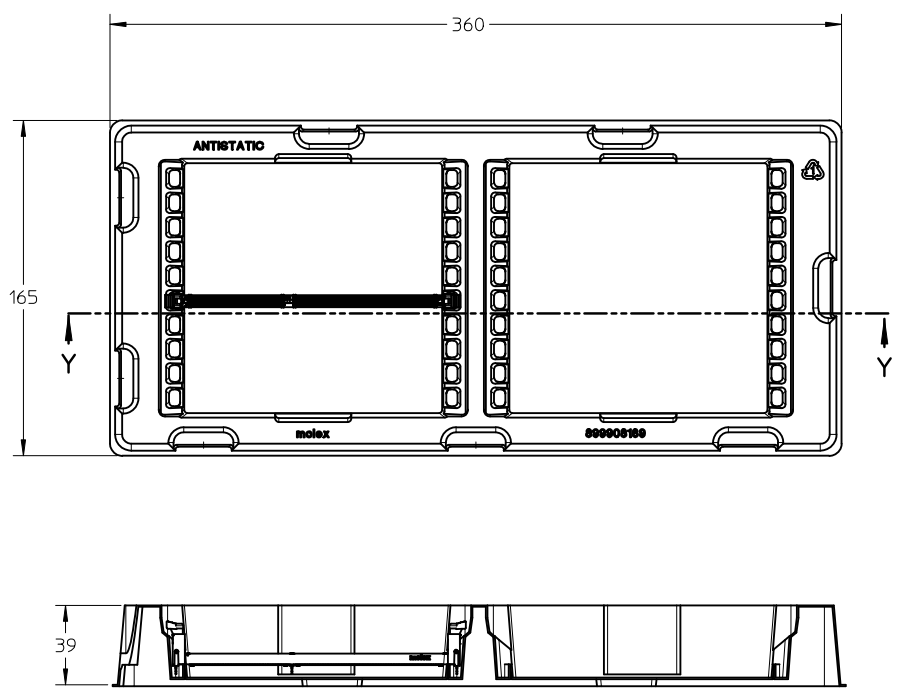
10 9 8 7 6 5 4 3 2 1

VIEW FOR PACKAGING TRAY



SECTION Z-Z

TRAY A - NO. OF CAVITY = 2 X 16 = 32PCS



SECTION Y-Y

AMD. JEDEC STD. NO. EC NO: S2011-0743 DRW:CCTEH CHKD:CGTAN APPR:SHLENI	REV 2	DESCRIPTION 2011/02/25 2011/04/19 2011/04/19	QUALITY SYMBOLS $F_{\Delta}=0$ $F_{\square}=0$ $F_{\nabla}=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
				mm	INCH	BROWN - NO. OF CAVITY JAKEEMW 2009/04/22	TITLE X 10 = 20PCS		
				4 PLACES ± --- ± ---	CHECKED BY CCTEH	DATE 2009/05/27	DDR3 DIMM, 1.00 PITCH 240CKTS, LSP, STD LATCH SMT, VERTICAL, LOWLLCR		
				3 PLACES ± --- ± ---	APPROVED BY SHLENI	DATE 2009/05/27	MOLEX INCORPORATED		
				2 PLACES ± 0.20 ± ---	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-78507-001	SHEET NO. 5 OF 6	
				1 PLACE ± --- ± ---	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
				ANGULAR ± 3 °					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS									

9 8 7 6 5 4 3 2 1

PART NO.	VOLTAGE KEY POS.	DIM 'X'	PLATING OPTION	LATCH COLOR	TRAY TYPE	LUBRICATION
78507-0001	CENTER (1.5V)	3.94	0.76µM (30µNCH) MIN. GOLD ON CONTACT. 2.54µM (100µNCH) MIN. PURE TIN ON SOLDER TAIL. 1.27µM (50µNCH) MIN. NICKEL UNDERPLATE.	BLACK	B	YES
78507-0002					A	
78507-0003				B		
78507-0004				A		

AMD, JEDEC STD. NO. EC NO: S2011-0743 DRW: CCTEH 2011/02/25 CHKD: GTAN 2011/04/19 APPR: SHLENI 2011/04/19 2	QUALITY SYMBOLS $\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± ---	mm INCH	DRAWN BY JAKEEMEW	DATE 2009/04/22	TITLE DDR3 DIMM, 1.00 PITCH 240CKTS, LSP, STD LATCH SMT, VERTICAL, LOWLLCR			
		ANGULAR ± 3 °		CHECKED BY CCTEH	DATE 2009/05/27	APPROVED BY SHLENI			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE	DATE 2009/05/27	MOLEX INCORPORATED		DOCUMENT NO. SD-78507-001	SHEET NO. 6 OF 6